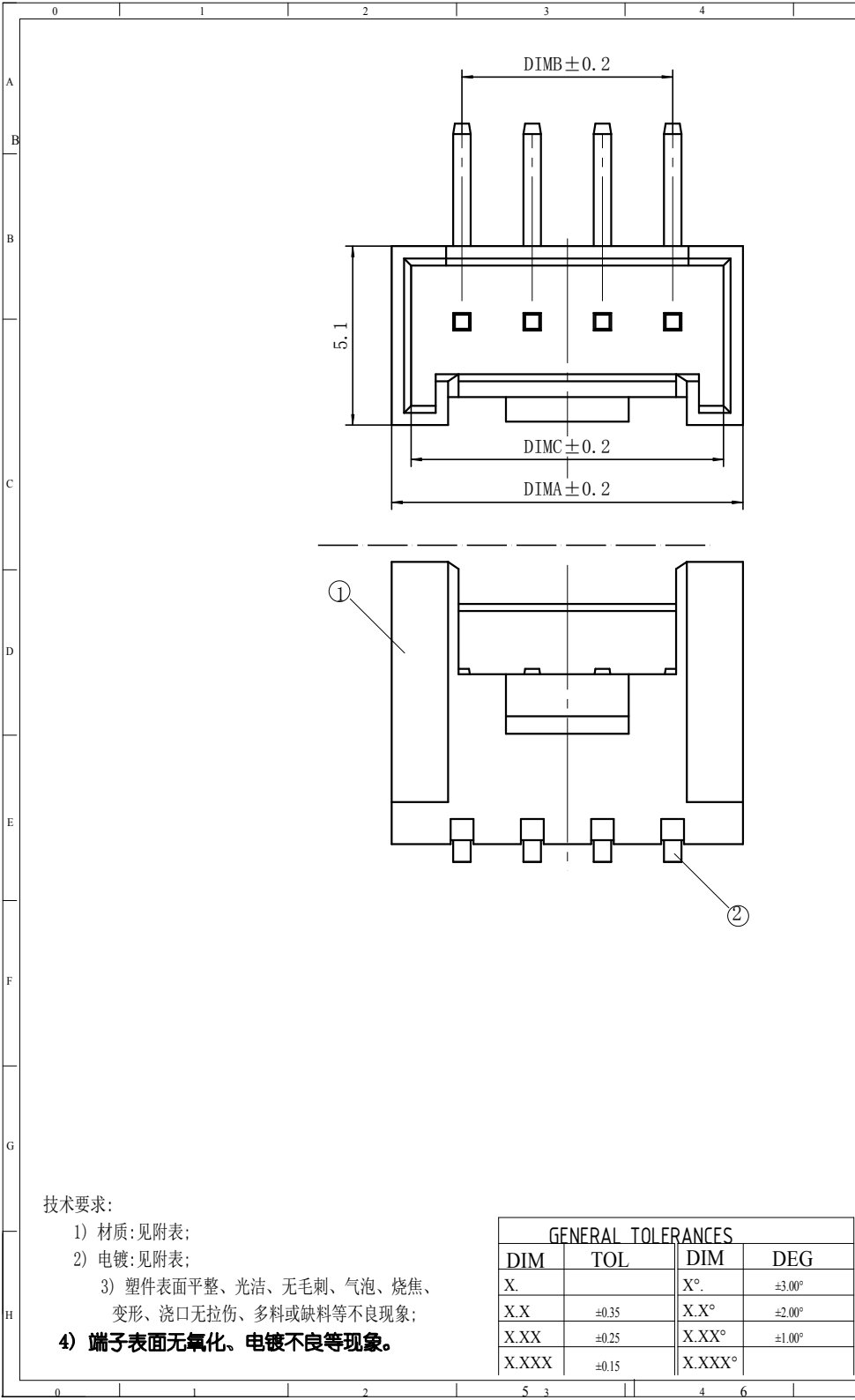
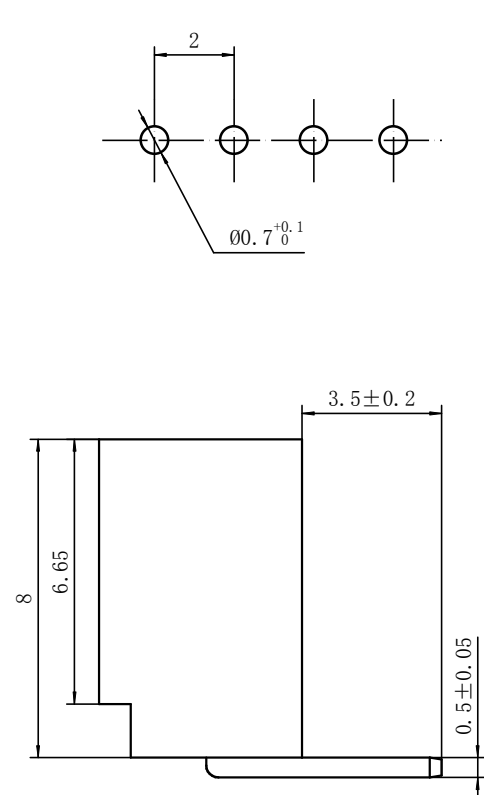


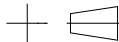


REV.	EC#	DESCRIPTION	DATE	DRAWN	CHECK	APPROVED
		初版发行	2020-05-28			



适应基板厚度: 1.2mm~1.6mm
温度范围: -25℃~85℃
额定电压: 250V AC/DC
额定电流: 1A
绝缘电阻: ≥1000MΩ
耐压: 800V AC/minute

15P	32.0	28.0	30.9
14P	30.0	26.0	28.9
13P	28.0	24.0	26.9
12P	26.0	22.0	24.9
11P	24.0	20.0	22.9
10P	22.0	18.0	20.9
9P	20.0	16.0	18.9
8P	18.0	14.0	16.9
7P	16.0	12.0	14.9
6P	14.0	10.0	12.9
5P	12.0	8.0	10.9
4P	10.0	6.0	8.9
3P	8.0	4.0	6.9
2P	6.0	2.0	4.9
NUMBER OF PINS	DIM A	DIM B	DIM C

2	PIN	n PCS	材质:铜合金, 电镀:镀亮锡60u"MIN						
1	Housing	1 PCS	材质:PA66 (UL94V-0)						
NO.	NAME	Q'TY	DESCRIPTION						
			 连兴旺电子(深圳)有限公司 LXWCONN ELECTRONICS (SHENZHEN) CO. , LTD						
DRAW :		2020-05-28	TITLE: HY2.0AW WAFER DIP		DRAW NAME: HY-XXAW				
DESIGN:		2020-05-28							
CHECK:		2020-05-28	SERIES: HY2.0 SERIES		DRAW NO.				
APPROVED		2020-05-28	P/N:						
CUSTOMER DRAWING			REV. 1.00	SCALE N/A	UNIT: mm	SHEET: 1/1			
7		8		9		10		11	